TOSHIBA Field Effect Transistor Silicon N-Channel MOS Type (π -MOSIV)

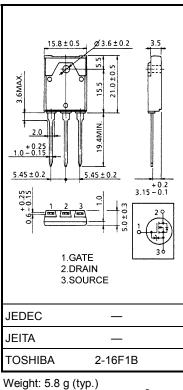
2SK3880

Switching Regulator Applications

- Low drain-source ON resistance: $RDS(ON) = 1.35 \Omega$ (typ.)
- High forward transfer admittance: $|Y_{fs}| = 5.2 \text{ S (typ.)}$
- Low leakage current: $IDSS = 100 \,\mu A (max) (VDS = 640 \,V)$
- Enhancement model: $V_{th} = 2.0 \sim 4.0 \text{ V}$ (V_{DS} = 10 V, I_D = 1 mA)

Maximum Ratings (Ta = 25°C)

Characteristics			Symbol	Rating	Unit	
Drain-source voltage			V _{DSS}	800	V	
Drain-gate voltage ($R_{GS} = 20 \text{ k}\Omega$)			V _{DGR}	800	V	
Gate-source voltage			V _{GSS}	±30	V	
Drain current	DC	(Note 1)	Ι _D	6.5	А	
	Pulse	(Note 1)	I _{DP}	19.5	~	
Drain power dissipation (Tc = 25° C)			PD	80	W	
Single pulse avalanche energy (Note 2)			E _{AR}	375	mJ	
Avalanche current			I _{AR}	6.5	А	
Repetitive avalanche energy (Note 3)			E _{AR}	8	mJ	
Channel temperature			T _{ch}	150	°C	
Storage temperature range			T _{stg}	-55~150	°C	



Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	1.56	°C/W
Thermal resistance, channel to ambient	R _{th (ch-a)}	41.6	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C during use of the device.

Note 2: $V_{DD} = 90 \text{ V}, \text{ T}_{ch} = 25^{\circ}\text{C}$ (initial), L = 16.1 mH, R_G = 25 Ω , I_{AR} = 6.5 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature

This transistor is an electrostatic-sensitive device. Handle with care.



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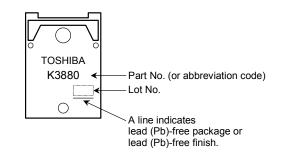
Electrical Characteristics (Ta = 25°C)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		I _{GSS}	$V_{GS}=\pm 25~V,~V_{DS}=0~V$	_		±10	μA
Drain-source breakdown voltage		V (BR) GSS	$I_G=\pm 10~\mu A,~V_{DS}=0~V$	±30			V
Drain cutoff curre	Drain cutoff current		$V_{DS} = 640 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	_		100	μA
Drain-source breakdown voltage		V (BR) DSS	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	800			V
Gate threshold voltage		V _{th}	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 1 \text{ mA}$	2.0		4.0	V
Drain-source ON resistance		R _{DS (ON)}	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 3.5 \text{ A}$		1.35	1.7	Ω
Forward transfer admittance		Y _{fs}	$V_{DS} = 20 \text{ V}, \text{ I}_{D} = 3.5 \text{ A}$	2.5	5.2		S
Input capacitance		C _{iss}		_	1500		pF
Reverse transfer capacitance		C _{rss}	V_{DS} = 25 V, V_{GS} = 0 V, f = 1 MHz	_	25	—	
Output capacitance		C _{oss}		_	140	_	
Switching time	Rise time	tr	$V_{GS}^{10 V}$ 0 V $C_{GS}^{10 V}$ $C_{GS}^{10 V}$ $R_{L}= 114 \Omega$ $V_{OD} \approx 400 V$	_	35	_	- ns
	Turn-on time	t _{on}			80	_	
	Fall time	t _f	Duty \leq 1%, t _w = 10 μ s	_	50	_	
	Turn-off time	t _{off}		_	220	_	
Total gate charge (gate-source plus gate-drain)		Qg			35	—	nC
Gate-source charge		Q _{gs}	$V_{DD} \simeq 400 \text{ V}, \text{ V}_{GS} = 10 \text{ V}, \text{ I}_{D} = 6.5 \text{ A}$	_	22	_	
Gate-drain ("Miller") charge		Q _{gd}		_	13	_	

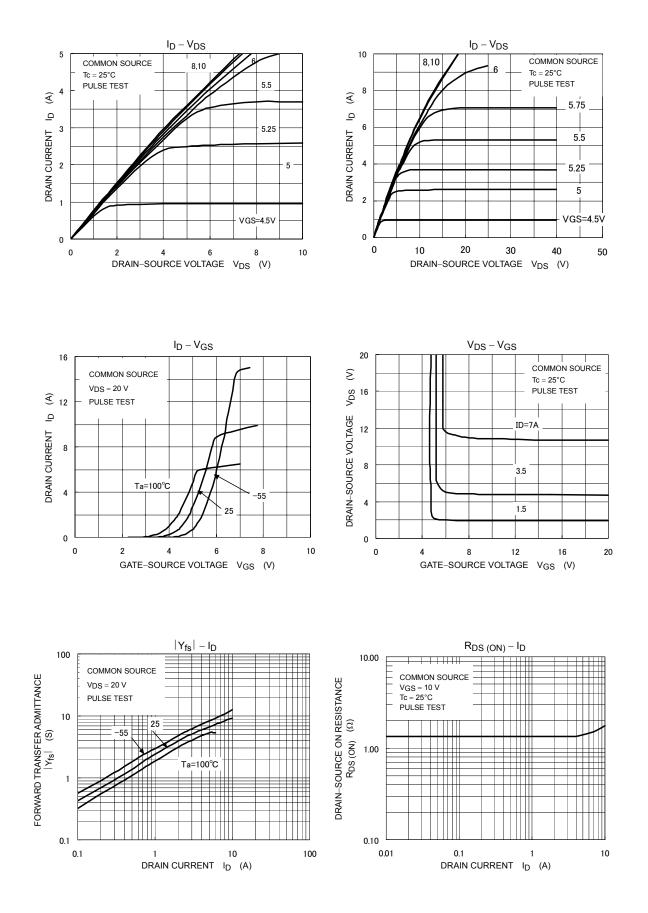
Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	—	_	_	6.5	А
Pulse drain reverse current (Note 1)	I _{DRP}	—	_	_	19.5	А
Forward voltage (diode)	V _{DSF}	$I_{DR} = 6.5 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	-1.7	V
Reverse recovery time	t _{rr}	$I_{DR} = 6.5 \text{ A}, V_{GS} = 0 \text{ V},$	_	1200	_	ns
Reverse recovery charge	Q _{rr}	dI _{DR} /dt = 100 A/μs		11.5		μC

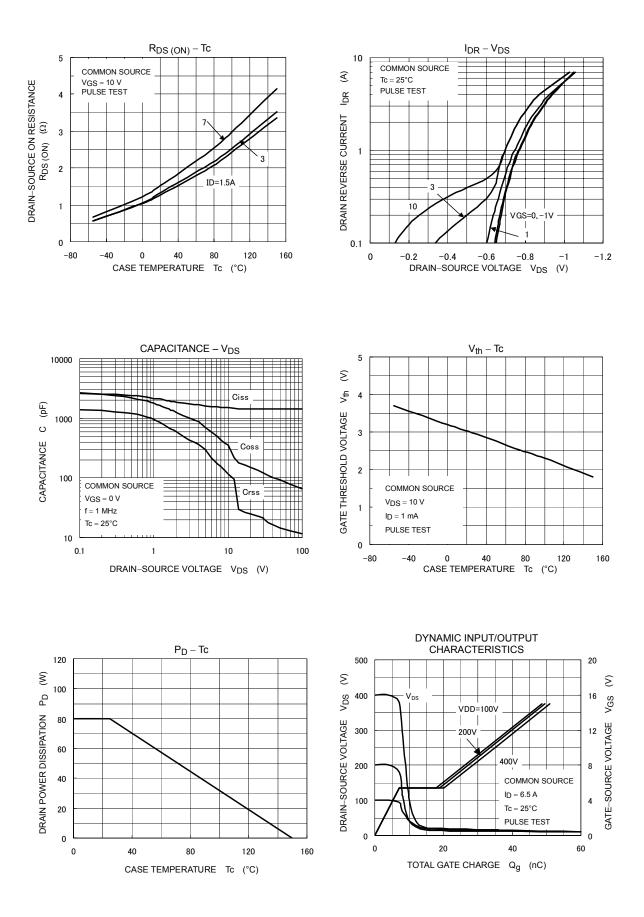
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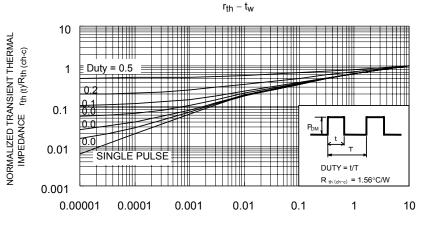


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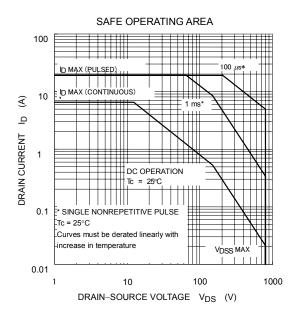


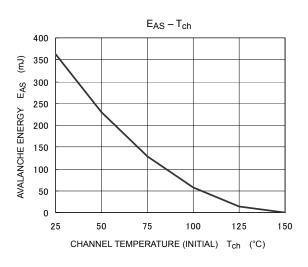
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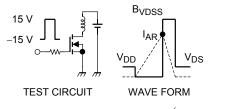














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